



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Donald Craig Foster
Assignee: Amkor Technology, Inc.
Title: Stackable Lead Frame Package Using Exposed Internal Lead Traces
Serial No.: 09/829,341 Filing Date: April 9, 2001
Examiner: Tuan T. Dinh Group Art Unit: 2827
Docket No.: M-9950 US

RECEIVED
DEC -4 2002
TC 2800 MAIL ROOM

San Jose, California
November 21, 2002

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

RESPONSE TO OFFICE ACTION MAILED JUNE 19, 2002

Dear Sir:

Applicant responds to the Office Action mailed June 19, 2002 with the following amendments and remarks.

IN THE CLAIMS

Please amend claim 1 to read as follows. The changes to claim 1 are shown in an Appendix hereto. Below is a list of all of the now pending claims.

1. (Amended) A semiconductor die package, comprising:

conductive outer leads having first ends extending outside an encapsulant body of the package and second ends extending into an interior of the encapsulant body of the package;

conductive inner leads within the encapsulant body and having first ends extending to and electrically accessible through a first surface of the encapsulant body of the package; and

LAW OFFICES OF
SKJERVEN MORRELL LLP
25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979